Electronic Patent Application Fee Transmittal							
Application Number:	10715641						
Filing Date:	18-Nov-2003						
Title of Invention:	Raised solder-mask-defined (SMD) solder ball pads for a laminate electronic circuit board						
First Named Inventor/Applicant Name:	Tz-Cheng Chiu						
Filer:	Yingsheng Tung/Jackie McBride						
Attorney Docket Number:	TI-36052 (1962-07500)						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 3 months with \$0 paid		1253	1	1020	1020		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			1020